

Qplast™

QPHD WO695F

High Density Polyethylene

Qplast™ QPHD WO695F is a blown film resin made from high-density polyethylene with a high molecular weight. Films produced from QPHD WO695F resin demonstrate exceptional impact resistance, toughness, and stiffness. QPHD WO695F resin is especially suitable for films with a thickness of less than 0.5 mil.

Supplier



Applications

- Blown Film
- Trash Bags
- Trash Can Liners
- Heavy Duty Bags
- Grocery Sacks
- Industrial Applications

Form(s)

Pellets

Resin Properties

	Typical Value (English)	Typical Value (SI)	Test Method
Density	0.951 g/cm ³	0.951 g/cm ³	ASTM D1505
Melt Index (190°C/2.16 kg)	0.060 g/10 min	0.060 g/10 min	ASTM D1238
High Load Melt Index (190°C/21.6 kg)	9.1 g/10 min	9.1 g/10 min	ASTM D1238
Melting Temperature	266 °F	130 °C	DSC

Film Properties

Tensile Strength at Yield MD	5400 psi	37 MPa	ASTM D882
Tensile Strength at Yield TD	4700 psi	32 MPa	ASTM D882
Tensile Strength at Break MD	12500 psi	86 MPa	ASTM D882
Tensile Strength at Break TD	10500 psi	72 MPa	ASTM D882
Elongation at Break MD	290 %	290 %	ASTM D882
Elongation at Break TD	390 %	390 %	ASTM D882
Secant Modulus MD — 1% Secant	151000 psi	1041 MPa	ASTM D882
Secant Modulus TD — 1% Secant	160000 psi	1100 MPa	ASTM D882
Dart Drop Impact	300 g	300 g	ASTM D1709A
Elmendorf Tear Strength MD	7 g	7 g	ASTM D1922
Elmendorf Tear Strength TD	40 g	40 g	ASTM D1922

Disclaimer

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